

Developed for Power Device Package that needs Good Heat Dissipation Through Molding Compound.

Strong Points

- a) High Thermal Conductivity with Good Moldability, Excellent Moisture Resistance and Low Stress.
- b) Used in Auto Molding System by Rapid Cure Grades.
- c) KE-870 and KE-880 is Formulated with Special High Thermal Conductivity Filler System and Achieve High Thermal Conductivity (above 3W/m K).

Application

- a) Isolation Packages such as TO-220 and TO-3P that need Heat Dissipation Characteristics.
- b) Packages for High Heating Volume such as Power Module.

General Properties

Item	Units	KE-850SH	KE-850SP	KE-870	KE-880
Spiral flow	cm	35	50	50	45
Gel time	s	25	35	35	35
Specific gravity	-	2.2	2.2	2.4	2.7
C.T.E	$\times 10^{-5}/^{\circ}\text{C}$	2.2	2.1	1.5	1.3
		5.9	5.9	6.6	5.0
Glass transition temp.	$^{\circ}\text{C}$	175	190	160	170
Thermal conductivity	W/mK	2.3	2.3	3.4	4.1

